











## Mounting IC Packages for Sample Preparation

RKD Engineering's **Mount Plate** is a unique hot plate used for mounting integrated circuit packages with special wax. Packages are mounted in preparation for precavitation, heat spread/sink removals, specialized mechanical preparations and other typical usages for high temperature heating.

The **Mount Plate** heats the metal holding fixture at a programmable rate to prevent thermal damage to the sample being mounted. When the melting point of the wax is reached, the operator is prompted to mount and align the sample. The device then cools



the holding fixture at a controlled rate, setting the mounting wax. When the sample is cooled to an ambient temperature, the operator is prompted to remove the mounted device and holder.

The **Mount Plate 5800** allows fast and accurate sample mounting. It receives standard RKD Engineering part holding fixtures and can be operated under a microscope for precision part alignment.



## **Features**

- Accurately controlled sample temperature
- Controlled heating rate to minimize thermal stress
- Controlled cooling rate
- Fast cycling
- Easy to use operator interface
- Special cycle for manual acid decapsulation
- Low profile can be placed under a microscope

## Mount Plate 5800



## Specifications

Dimensions	Height: 133 mm (5.25 in)
	Width: 165 mm (6.5 in)
	Depth: 280 mm (11 in)
Weight	Approx. 3 kg (7 lb)
Power Source	90 to 250 VAC, 50 to 60 Hz (4 amp)
Temperature Range	30° to 140° C
Heating Up Rate	0.1° to 0.8° C/s
Cooling Down Rate	0.1° to 0.8° C/s
Soak Time	1 to 60 s
Rest Temperature	30° C nominal
Temperature Accuracy	+/- 1° C